PCN Number:	20170619000	**PCN Date:**	June 27 2017
Title:	Qualification of an additional Substrate Manufacturing Subcontractor for the TPS82130SIL		
Customer Contact:	PCN Manager	**Dept:**	Quality Services
Proposed 1st Ship Date:	Sept 27 2017	**Estimated Sample Availability:**	Provided upon Request

Change Type:

☒	Assembly Site	☒	Assembly Process	☒	Assembly Materials
☐	Design	☐	Electrical Specification	☐	Mechanical Specification
☐	Test Site	☐	Packing/Shipping/Labeling	☐	Test Process
☐	Wafer Bump Site	☐	Wafer Bump Material	☐	Wafer Bump Process
☐	Wafer Fab Site	☐	Wafer Fab Materials	☐	Wafer Fab Process
		☐	Part number change		

PCN Details

Description of Change:

TI is qualifying an additional substrate manufacturing subcontractor (ACCESS) for TPS82130SIL. Construction differences are as follows:

What	Current (ATNS)	New (ACCESS)
Substrate Material	R1570	**SD#EN02J01037A**
Solder mask	XV501T	**SR7300G**
Adhesive	SID#704654	**N/A**
Cavity Filler	N/A	**SD#ABF GX-T31**

Reason for Change:

Continuity of Supply

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

None

Anticipated impact on Material Declaration

☐	No Impact to the Material Declaration	☒	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained from the TI ECO website.

Changes to product identification resulting from this PCN:

None

Product Affected

TPS82130SILR	TPS82130SILT

Qualification Report

TPS82130SIL, TPS82140SIL, TPS82150SIL Qualification Memo
Approve Date 02-May-2017

Product Attributes

Attributes	Qual Device: TPS82130SIL	QBS Product Reference: TPS82130SIL	QBS Process Reference: TPS62110RSA
Assembly Site	PTI-TAIWAN	PTI-TAIWAN	CAR
Package Family	MicroSIP	MicroSIP	QFN
Flammability Rating	UL 94 V-0	UL 94 V-0	UL 94 V-0
Wafer Fab Supplier	MIHO8-CLARK/BP	MIHO8-CLARK/BP	MIHO8
Wafer Process	LBC7	LBC7	LBC7

- QBS: Qual By Similarity
- Qual Device TPS82130SIL is qualified at LEVEL2-260C

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: TPS82130SIL	QBS Product Reference: TPS82130SIL	QBS Process Reference: TPS62110RSA
AC	Autoclave 121C	96 Hours	-	-	3/231/0
ED	Electrical Characterization	Per Datasheet Parameters	Pass	Pass	-
ELFR	Early Life Failure Rate, 140C	48 Hours	-	-	3/1881/0
FLAM	Flammability (IEC 695-2-2)	--	1/5/0	-	-
FLAM	Flammability (UL 94V-0)	--	1/5/0	-	-
FLAM	Flammability (UL-1694)	--	1/5/0	-	-
HAST	Biased HAST, 110C/85%RH	264 Hours	2/154/0	-	-
HAST	Biased HAST, 130C/85%RH	96 Hours	-	1/77/0	3/231/0
HBM	ESD - HBM	2500 V	1/3/0	1/3/0	-
CDM	ESD - CDM	1500 V	1/3/0	1/3/0	-
HTOL	Life Test, 125C	1000 Hours	3/266/0	-	-
HTOL	Life Test, 140C	480 Hours	-	-	3/231/0
HTSL	High Temp Storage Bake 150C	1000 Hours	3/240/0	3/231/0	-
HTSL	High Temp Storage Bake 170C	420 Hours	-	-	3/231/0
LU	Latch-up	(per JESD78)	-	1/8/0	3/15/0
PD	Physical Dimensions	--	Pass	Pass	-
SD	Solderability	8 Hours Steam Age	3/66/0	-	-
TC	Temperature Cycle, -55/125C	700 Cycles	3/231/0	3/231/0	-
TC	Temperature Cycle, -65/150C	500 Cycles	-	-	3/231/0
TS	Thermal Shock, -65/150C	500 Cycles	-	-	3/231/0
UHAST	Unbiased HAST 110C/85%RH	264 Hours	3/231/0	-	-
UHAST	Unbiased HAST 130C/85%RH	96 Hours	-	3/231/0	-

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
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